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Intelligent Power Module (IPM) 1200 V, 5 A

Advance Information

NFAM0512L5B

General Description

The NFAM0512L5B is a fully-integrated inverter power module consisting of an independent High side gate driver, LVIC, six IGBT's and a temperature sensor (VTS), suitable for driving permanent magnet synchronous (PMSM) motors, brushless DC (BLDC) motors and AC asynchronous motors. The IGBT's are configured in a three-phase bridge with separate emitter connections for the lower legs for maximum flexibility in the choice of control algorithm.

The power stage has under-voltage lockout protection (UVP). Internal boost diodes are provided for high side gate boost drive.

Features

- Three–phase 1200 V, 5 A IGBT Module with Independent Drivers
- Active Logic Interface
- Built-in Under-voltage Protection (UVP)
- Integrated Bootstrap Diodes and Resistors
- Separate Low-side IGBT Emitter Connections for Individual Current Sensing of Each Phase
- Temperature Sensor (VTS)
- UL1557 Certified (File No.339285)
- This Device is Pb-Free and RoHS Compliant

Typical Application

- Industrial Drives
- Industrial Pumps
- Industrial Fans
- Industrial Automation

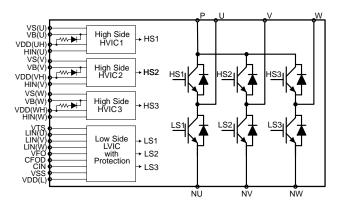
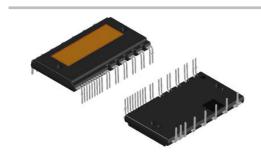


Figure 1. Application Schematic



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DIP39, 54.5x31.0 EP-2 CASE MODGX

MARKING DIAGRAM

O NFAM0512L5B O ZZZATYWW

Device marking is on package top side

NFAM0512L5B = Specific Device Code
ZZZ = Assembly Lot Code
A = Assembly Location
T = Test Location
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping [†] (Qty / Packing)		
NFAM0512L5B	DIP39, 31.0x54.5 (Pb-Free)	90 / BOX		

This document contains information on a new product. Specifications and information herein are subject to change without notice.

APPLICATION SCHEMATIC

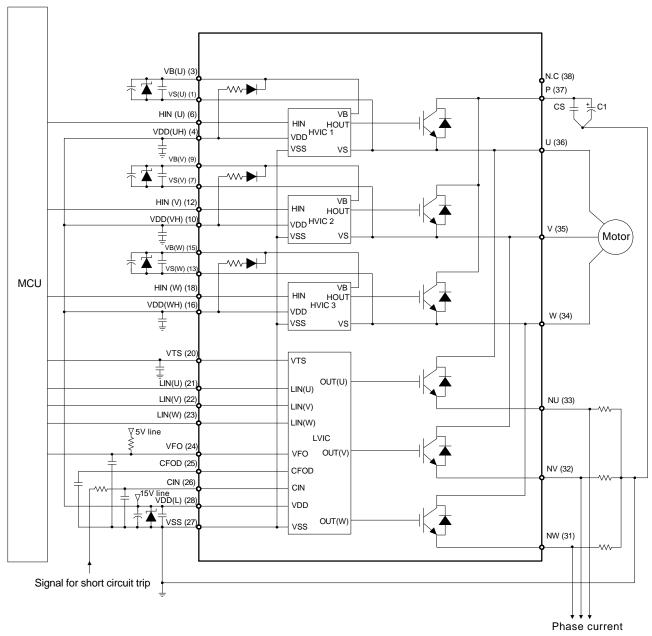


Figure 2. Application Schematic - Adjustable Option

BLOCK DIAGRAM

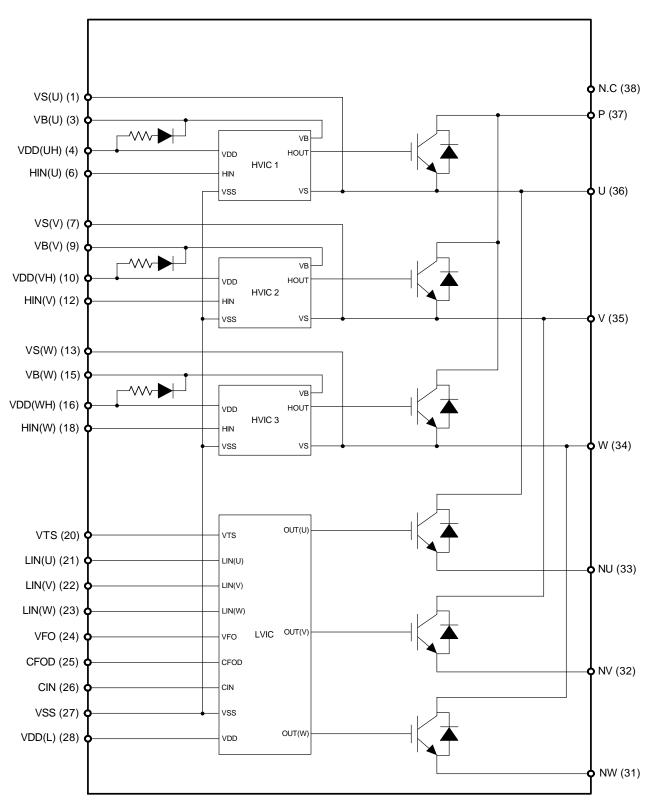


Figure 3. Equivalent Block Diagram

PIN FUNCTION DESCRIPTION

Pin	Name	Description
1	VS(U)	High-Side Bias Voltage GND for U Phase IGBT Driving
(2)	ı	Dummy
3	VB(U)	High-Side Bias Voltage for U Phase IGBT Driving
4	VDD(UH)	High-Side Bias Voltage for U Phase IC
(5)	-	Dummy
6	HIN(U)	Signal Input for High-Side U Phase
7	VS(V)	High–Side Bias Voltage GND for V Phase IGBT Driving
(8)	-	Dummy
9	VB(V)	High–Side Bias Voltage for V Phase IGBT Driving
10	VDD(VH)	High-Side Bias Voltage for V Phase IC
(11)	-	Dummy
12	HIN(V)	Signal Input for High–Side V Phase
13	VS(W)	High-Side Bias Voltage GND for W Phase IGBT Driving
(14)	-	Dummy
15	VB(W)	High-Side Bias Voltage for W Phase IGBT Driving
16	VDD(WH)	High-Side Bias Voltage for W Phase IC
(17)	-	Dummy
18	HIN(W)	Signal Input for High–Side W Phase
(19)	-	Dummy
20	VTS	Voltage Output for LVIC Temperature Sensing Unit
21	LIN(U)	Signal Input for Low–Side U Phase
22	LIN(V)	Signal Input for Low–Side V Phase
23	LIN(W)	Signal Input for Low–Side W Phase
24	VFO	Fault Output
25	CFOD	Capacitor for Fault Output Duration Selection
26	CIN	Input for Current Protection
27	VSS	Low-Side Common Supply Ground
28	VDD(L)	Low–Side Bias Voltage for IC and IGBTs Driving
(29)	-	Dummy
(30)	-	Dummy
31	NW	Negative DC-Link Input for U Phase
32	NV	Negative DC-Link Input for V Phase
33	NU	Negative DC-Link Input for W Phase
34	W	Output for U Phase
35	V	Output for V Phase
36	U	Output for W Phase
37	Р	Positive DC–Link Input
38	N.C	No Connection
(39)	_	Dummy

Pins of () are the dummy for internal connection. These pins should be no connection.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$) (Note 2)

Rating	Symbol	Conditions	Value	Unit
Supply Voltage	VPN	P – NU, NV, NW	900	V
Supply Voltage (Surge)	VPN(Surge)	P – NU, NV, NW, (Note 3)	1000	V
Self Protection Supply Voltage Limit (Short–Circuit Protection Capability	VPN(PROT)	$VDD = VBS = 13.5 \text{ V} \sim 16.5 \text{ V},$ Tj = 150°C, Vces < 1200 V, Non–Repetitive, < 2 μs	800	V
Collector-Emitter Voltage	Vces		1200	V
Maximum Repetitive Revers Voltage	VRRM		1200	V
Each IGBT Collector Current	±lc		±5	Α
Each IGBT Collector Current (Peak)	±lcp	Under 1 ms Pulse Width	±10	Α
Control Supply Voltage High-Side	VDD	VDD(UH, VH, WH), VDD(L) – VSS –0.3 to 2		V
Control Bias Voltage	VBS	VB(U) - VS(U), $VB(V) - VS(V)$, $VB(W) - VS(W)$	-0.3 to 20	V
Input Signal Voltage	VIN	HIN(U), HIN(V), HIN(W), LIN(U), LIN(V), LIN(W) – VSS	-0.3 to VDD	V
Fault Output Supply Voltage	VFO	VFO – VSS	-0.3 to VDD	V
Fault Output Current	IFO	Sink Current at VFO pin	2	mA
Current Sensing Input Voltage	VCIN	CIN - VSS	-0.3 to VDD	V
Corrector Dissipation	Pc	Per One Chip	59	W
Operating Junction Temperature	Ti		-40 to +150	°C
Storage Temperature	Tstg		-40 to +125	°C
Module Case Operation Temperature	Tc		-40 to +125	°C
Isolation Voltage	Viso	60 Hz, Sinusoidal, AC 1 minute, Connection Pins to Heat Sink Plate	2500	V rms

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe

THERMAL CHARACTERISTICS

Rating	Symbol	Conditions	Min	Тур	Max	Unit
Junction to Case Thermal	Rth(j-c)Q	Inverter IGBT Part (per 1/6 Module)	-	-	2.1	°C/W
Resistance	Rth(j-c)F	Inverter FRD Part (per 1/6 Module)	_	_	2.6	°C/W

^{4.} Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe Operating parameters.

RECOMMENDED OPERATING RANGES (Note 6)

Rating	Symbol	Conditions	Min	Тур	Max	Unit
Supply Voltage	VPN	P – NU, NV, NW	-	600	800	V
Gate Driver Supply Voltages	VDD	VDD(UH, VH, WH), VDD(L) – VSS	13.5	15	16.5	V
	VBS	VB(U) - VS(U), $VB(V) - VS(V)$, $VB(W) - VS(W)$	13.0	15	18.5	V
Supply Voltage Variation	dVDD / dt dVBS / dt		-1	-	1	V/μs
PWM Frequency	fPWM		1		20	kHz
Dead Time	DT	Turn-off to Turn-on (external)	3	-	-	μs

Operating parameters.

^{3.} This surge voltage developed by the switching operation due to the wiring inductance between P and NU, NV, NW terminal.

RECOMMENDED OPERATING RANGES (Note 6) (continued)

Rating	Symbol	Conditions		Min	Тур	Max	Unit
Allowable r.m.s. Current	lo	VPN = 600 V, VDD = VBS = 15 V, P.F. = 0.8.	f _{PWM} = 5 kHz	ı	ı	7.7	A rms
	Tc ≤ 125	Tc ≤ 125°C, Tj ≤ 150°C, (Note 5)	f _{PWM} = 15 kHz	-	-	4.0	
Allowable Input Pulse Width	Illowable Input Pulse Width PWIN (on) $400 \text{ V} \le \text{VPN} \le 800 \text{ V}, \\ 13.5 \text{ V} \le \text{VDD} \le 16.5 \text{ V},$			2.0	-	-	μs
	PWIN (off)	13.0 V ≤ VBS ≤ 18.5 V, -40°C ≤ Tc ≤ 150°C		2.5	-	-	
Package Mounting Torque		M3 Type Screw		0.6	0.7	0.9	Nm

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

- 5. Allowable r.m.s Current depends on the actual conditions.
- 6. Flatness tolerance of the heatsink should be within –50 μ m to +100 μ m.

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise noted) (Note 7)

P	arameter	Test Condition	Symbol	Min	Тур	Max	Unit	
INVERTER S	SECTION			•				
	nitter Leakage	Vce = Vces, Tj = 25°C	Ices	_	_	1	mA	
Current		Vce = Vces, Tj = 150°C			_	-	10	mA
Collector–Emitter Saturation Voltage		VDD = VBS = 15 V, IN = 5 V Ic = 5 A, Tj = 25°C		VCE(sat)	-	1.75	2.5	V
		VDD = VBS = 15 V, IN = 5 V Ic = 5 A, Tj = 150°C			-	1.90		V
FWDi Forwa	rd Voltage	IN = 0 V, If = 5 A, Tj = 25°C		VF	_	1.70	2.5	V
		IN = 0 V, If = 5 A, Tj = 150°C	IN = 0 V, If = 5 A, Tj = 150°C			1.50		V
High Side	Switching Times		VPN = 600 V, VDD(H) = VDD(L) = 15 V			1.40	2.00	μS
		Ic = 5 A, Tj = 25°C, IN = 0 ⇔ 5 V Inductive Load		tc (on)	_	0.30	0.60	μS
				toff	-	2.00	2.70	μS
				tc (off)	-	0.20	0.60	μS
				trr	-	0.30	-	μS
Low Side	Switching Times	VPN = 600 V, VDD(H) = VDD(L) =	ton	0.90	1.50	2.10	μS	
		Ic = 5 A, Tj = 25°C, IN = 0 ⇔ 5 V Inductive Load		tc (on)	-	0.30	0.60	μS
			toff	-	2.10	2.80	μS	
			tc (off)	-	0.20	0.60	μS	
			trr	-	0.40	-	μS	
DRIVER SE	CTION	•						
Quiescent V	DD Supply Current	VDD(UH,VH,WH) = 15 V, HIN(U,V,W) = 0 V	VDD(UH) – VSS VDD(VH) – VSS VDD(WH) – VSS	IQDDH	-	-	0.30	mA
		VDD(L) = 15 V, LIN(U, V, W) = 0 V	VDD(L) - VSS	IQDDL	-	-	3.50	mA
Operating VDD Supply Current		VDD(UH, VH, WH) = 15 V, f _{PWM} = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High–Side	VDD(UH) - VSS VDD(VH) - VSS VDD(WH) - VSS	IPDDH	-	-	0.40	mA
		VDD(L) = 15 V, f _{PWM} = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for Low–Side	VDD(L) – VSS	IPDDL	-	-	9.00	mA

ELECTRICAL CHARACTERISTICS (Tc = 25°C, VDD = 15 V, VBS = 15 V, unless otherwise noted) (Note 7) (continued)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit	
DRIVER SECTION			•		•	•	
Quiescent VBS Supply Current	VBS = 15 V HIN(U, V, W) = 0 V	VB(U) - VS(U) VB(V) - VS(V) VB(W) - VS(W)	IQBS	-	-	0.30	mA
Operating VBS Supply Current	VDD = VBS = 15 V, f _{PWM} = 20 kHz, Duty = 50%, Applied to one PWM Signal Input for High-Side	VB(U) - VS(U) VB(V) - VS(V) VB(W) - VS(W)	IPBS	-	-	8.00	mA
ON Threshold Voltage	HIN(U, V, W) – VSS, LIN(U, V, W)	– VSS	VIN(ON)			2.6	V
OFF Threshold Voltage			VIN(OF)	0.8			V
Short Circuit Trip Level	VDD = 15 V, CIN-VSS		VCIN(ref)	0.46	0.48	0.50	V
Supply Circuit Under-Voltage	Detection Level		UVDDD	10.3		12.5	V
Protection	Reset Level	UVDDR	10.8		13.0	V	
	Detection Level	UVBSD	10.0		12.0	V	
	Reset Level	UVBSR	10.5		12.5	V	
Voltage Output for LVIC Temperature Sensing Unit	VTS-VSS = 10 nF, Temp. = 25°C		VTS	0.905	1.030	1.155	V
Fault Output Voltage	$VDD = 0$ V, $CIN = 0$ V, VFO Circuit: 10 k Ω to 5 V Pull-up		VFOH	4.9	-	-	V
	$VDD = 0$ V, $CIN = 1$ V, VFO Circuit: 10 k Ω to 5 V Pull–up	VFOL	-	-	0.95	V	
Fault-Output Pulse Width	CFOD = 22 nF	tFOD	1.6	2.4	_	ms	
BOOTSTRAP SECTION							
Bootstrap Diode Forward Current	If = 0.1 A		VF	3.4	4.6	5.8	V
Built-in Limiting Resistance			RBOOT	30	38	46	Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{9.} Values based on design and/or characterization.

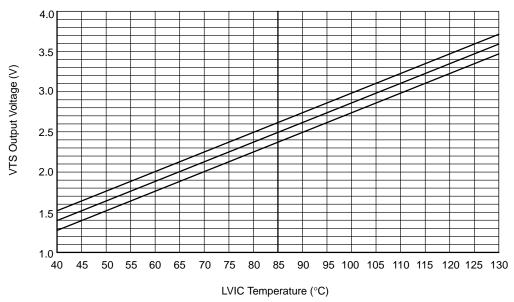


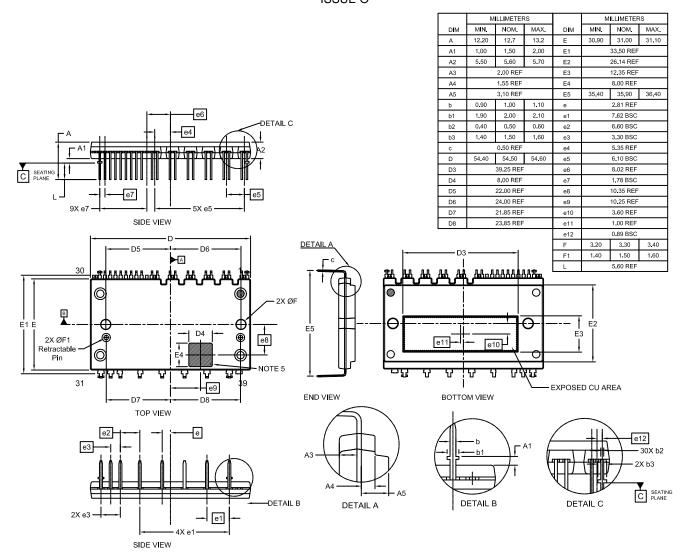
Figure 4. Temperature of LVIC versus VOT Characteristics

Performance guaranteed over the indicated operating temperature range by design and/or characterization tested at T_J = T_A = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

^{8.} The fault—out pulse width tFOD depends on the capacitance value of CFOD according to the following approximate equation: tFOD = 0.1 x 10⁶ x CFOD (s)

PACKAGE DIMENSIONS

DIP39, 54.5x31.0 EP-2 CASE MODGX ISSUE O



NOTES

- 1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
- 4. POSITION OF THE LEAD IS DETERMINED AT THE BASE OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.
- 5. AREA FOR 2D BAR CODE.
- 6. SHORTENED/CUT PINS ARE 2,5,8,11,14,17,19,29, 30 AND 39.

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